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## AMENDMENT TO THE CLAIMS

Please delete non-elected Claims 1-32.

Please add new Claim 45 as indicated below

33. (Original) A method of cleaning a chemical vapor deposition (CVD) reaction-chamber with cleaning gas provided through a remote plasma discharge chamber, comprising:

dissociating cleaning gas within the remote plasma discharge chamber by applying energy with a power of less than about 3,000 W;

supplying activated species from the remote plasma discharge chamber to the reaction chamber through a piping;

removing adhered deposits from CVD reactions on a wall of the reaction chamber at a rate of greater than or equal to about 2.0 microns/minute.

- 34. (Original) The method of Claim 33, wherein the deposits on the reaction chamber wall comprise silicon nitride.
- 35. (Original) The method of Claim 33, wherein the cleaning gas comprises fluorine-containing gas and the activated species comprises fluorine active species.
- 36. (Original) The method of Claim 33, wherein the applied energy has a frequency between about 300 kHz and 500 kHz.
- 37. (Original) The method of Claim 33, wherein supplying activated species comprises flowing NF<sub>3</sub> through the remote plasma discharge chamber at a rate between about 0.5 slm and 1.5 slm.
- 38. (Original) The method of Claim 33, further comprising opening a valve on the piping after conducting a CVD reaction and prior to supplying activated species.
- 39. (Original) The method of Claim 38, wherein opening a valve comprises withdrawing a sealing element completely from a path to form an opening substantially as wide as internal surfaces of the piping.
- 40. (Original) The method of Claim 38, further comprising closing the valve after removing the adhered deposits.
- 41. (Original) A self-cleaning chemical vapor deposition (CVD) reactor, comprising a reaction chamber, a remote plasma discharge chamber connected to the reaction chamber by

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piping, a gaseous source of fluorine in fluid communication with the piping upstream of the remote plasma discharge chamber, the piping comprises a through-flow type valve positioned between the remote plasma discharge chamber and the reaction chamber, and a power source communicating energy with a frequency between about 300 kHz and 500 kHz to activate fluorine within the remote plasma discharge chamber.

- 42. (Original) The CVD reactor of Claim 41, wherein wherein a pressure drop is formed across the valve when fully opened and plasma is ignited within the remote plasma discharge chamber, the pressure drop being less than about 5% of a pressure at an inlet to the chamber.
- 43. (Original) The CVD reactor of Claim 42, wherein the pressure drop is less than about 1% of the pressure at the inlet.
- 44. (Original) The CVD reactor of Claim 42, wherein an internal surface of the piping comprises a fluorine-passivated metal.
- 45. (New) The method of Claim 33, wherein dissociating comprises applying energy with a power between about 2,000 W and 3,000 W.